ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e *	* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi					ials and Mfg Information			
upplier Inform	ation													
Company name*			Company unique ID			τ	Unique ID Authority				Response Date*			
onsemi											2023-06-08			
Contact Name		Title - Contact			1	Phone - Contact*				Email - Contact*				
Product-Env-Stewar	rds		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
uthorized Represer	ntative*	Title - Representative			1	Phone - Representative*				Email - Representative*				
Product-Env-Stewar	rds	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requester	r Item Number	m Number Mfr Item Number Mfr Item Name FOD3150S 8PW 1A GD SMD		Mfr Item Name			Effective Dat	e Vers	sion	Manufacturing Site		Weight*	UOM	Unit Type
)		2023-06-08	LITEONFG			601.011	mg	Each		
	Proccess Information						l					l		
, , , , , , , , , , , , , , , , , , ,			Terminal Base Alloy J-STD-020 MS		SL Rating	Peak Process Body Temper		<u> </u>	·			per of Reflow Cyc	eles	
· ·	(Sn) - annealed	C	CU Alloy	1			260		C	30	secoi	nds 3		
omments														
	me at peak temperature													
or more informatio	on regarding material co	omposition j	please refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier has provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier has not or written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	4.011	mg	В	Gallium Arsenide (AsGa)	1303-00-0		0.281	mg
			Supplier	Silicon (Si)	7440-21-3		3.73	mg
Die Attach	0.25	mg	Supplier	Silver (Ag)	7440-22-4		0.1873	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.0627	mg
Lead Frame	113.441	mg	Supplier	Silver (Ag)	7440-22-4		0.7151	mg
			Supplier	Zinc (Zn)	7440-66-6		0.1362	mg
			Supplier	Iron (Fe)	7439-89-6		2.6124	mg
			Supplier	Copper (Cu)	7440-50-8		109.943	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0342	mg
Mold Compound-White	459.747	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		114.9368	mg
			В	Brominated Bisphenol A Diglycidyl Ether	40039-93-8		13.7924	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		62.0658	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		13.7924	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		229.8735	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		25.2861	mg
Plating	1.559	mg	Supplier	Tin (Sn)	7440-31-5		1.559	mg
Protective Coating	6.13	mg	Supplier	Poly(dimethylsiloxane), hydroxy terminated	70131-67-8		3.065	mg
			Supplier	Ethylbenzene	100-41-4		0.613	mg
			Supplier	Filler (SiO2)	68909-20-6		1.1647	mg
			Supplier	Misc.	Proprietary Data		0.0613	mg
			Supplier	Xylene	1330-20-7		1.226	mg
Wire Bond - Au	15.873	mg	Supplier	Gold (Au)	7440-57-5		15.873	mg